

THERMALLY ENHANCED COMPONENT SUBSTRATE: THERMAL BAR

ABSTRACT OF THE DISCLOSURE

An IC package dissipates thermal energy using thermal bars. The IC package includes a substrate material with a die pad area, which is suitable to support an integrated circuit. A plurality of solder ball pads is disposed on a first surface of the substrate material and a plurality of conductive thermal bars radiate outwardly from the die pad area and extend to the edge of the substrate component to facilitate the dissemination of thermal energy from the die pad area to the substrate and/or printed wiring board.